GL4910

■ Features

- 1. Small spot light diameter for easy beam diaphragming (*Apparent emission diameter : TYP. ϕ 0.32 mm)
- 2. Uniform emission intensity on chip emitting surface
- 3. Low peak forward voltage type

(Peak forward voltage V $_{FM}$: TYP. 1.7V)

*Expansion range on lens surface of infrared emitted from chips

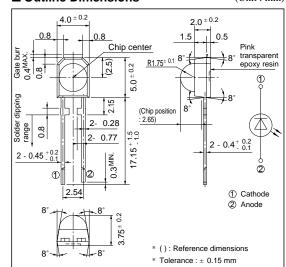
■ Applications

1. Cameras

Side View Type Infrared Emitting Diode for Camera AF (Automatic Focusing)

■ Outline Dimensions

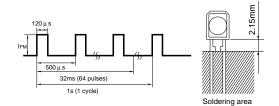
(Unit: mm)



■ Absolute Maximum Ratings

| = Absolute maximum ratings (1a=23 c) | | | | | | |
|--------------------------------------|------------------|--------------|------|--|--|--|
| Parameter | Symbol | Rating | Unit | | | |
| Forward current | I_F | 50 | mA | | | |
| *1 Peak forward current | I_{FM} | 1 | A | | | |
| Reverse voltage | VR | 4 | V | | | |
| Operating temperature | Topr | - 25 to + 60 | °C | | | |
| Storage temperature | T _{stg} | - 40 to + 85 | °C | | | |
| *2 Soldering temperature | Teol | 260 | °C | | | |

^{*1 30,00} cycles max. on pulse conditions shown in the right drawing



 $(Ta=25^{\circ}C)$

^{*2} For 5 seconds at the position of 2.15 mm from the resin edge



■ Electro-optical Characteristics

(Ta=25 °C)

| Parameter | Symbol | Conditions | MIN. | TYP. | MAX. | Unit |
|---------------------------|-----------------|--|------|------|------|------|
| Forward voltage | V _F | $I_F = 50 \text{mA}$ | - | 1.55 | 1.7 | V |
| Peak forward voltage | V _{FM} | $I_{FM} = 300 \text{mA}, t = 10 \text{ms}$ | - | 1.7 | 1.95 | V |
| Reverse current | I_R | $V_R = 1V$ | - | - | 100 | μΑ |
| Radiant flux | *3 Ф e | $I_{FM}=300mA,t=10ms$ | 4.2 | 9 | ı | mW |
| Peak emission wavelength | λp | $I_F = 50 \text{mA}$ | - | 850 | - | nm |
| Half intensity wavelength | Δλ | $I_F = 50 \text{mA}$ | - | 35 | - | nm |
| Half intensity angle | Δθ | $I_F = 50 \text{mA}$ | - | ± 32 | - | ۰ |
| Terminal capacitance | Ct | $V_R = 0$, $f = 1MH_Z$ | - | 80 | - | pF |

^{*3} Emission output to effective angle $\pm~25^{\circ}$

Fig. 1 Forward Current vs. Ambient Temperature

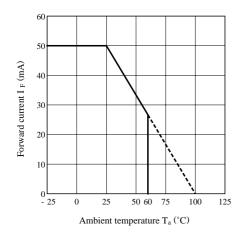


Fig. 2 Peak Forward Current vs. Duty Ratio

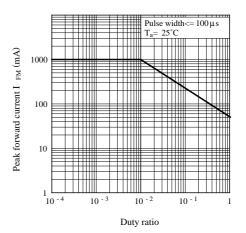


Fig. 3 Spectral Distribution

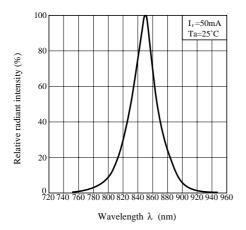


Fig. 5 Forward Current vs. Forward Voltage

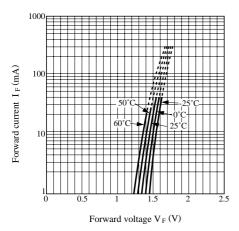


Fig. 7 Radiant Flux vs. Forward Current

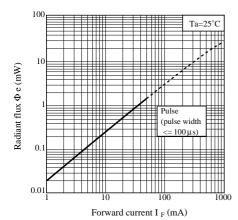


Fig. 4 Peak Emission Wavelength vs.
Ambient Temperature

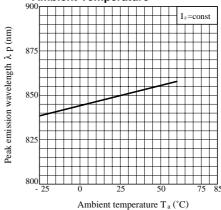


Fig. 6 Relative Radiant Flux vs. Ambient Temperature

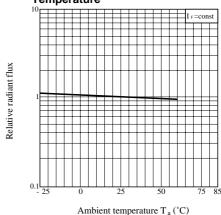
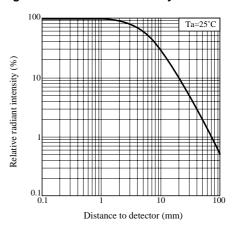
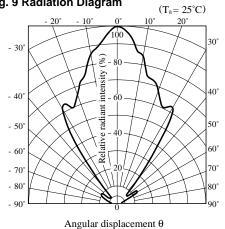


Fig. 8 Relative Radiant Intensity vs. Distance









• Please refer to the chapter "Precautions for Use". (Page 78 to 93)

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 - Consumer electronics
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 - Gas leakage sensor breakers
 - Alarm equipment
 - Various safety devices, etc.
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